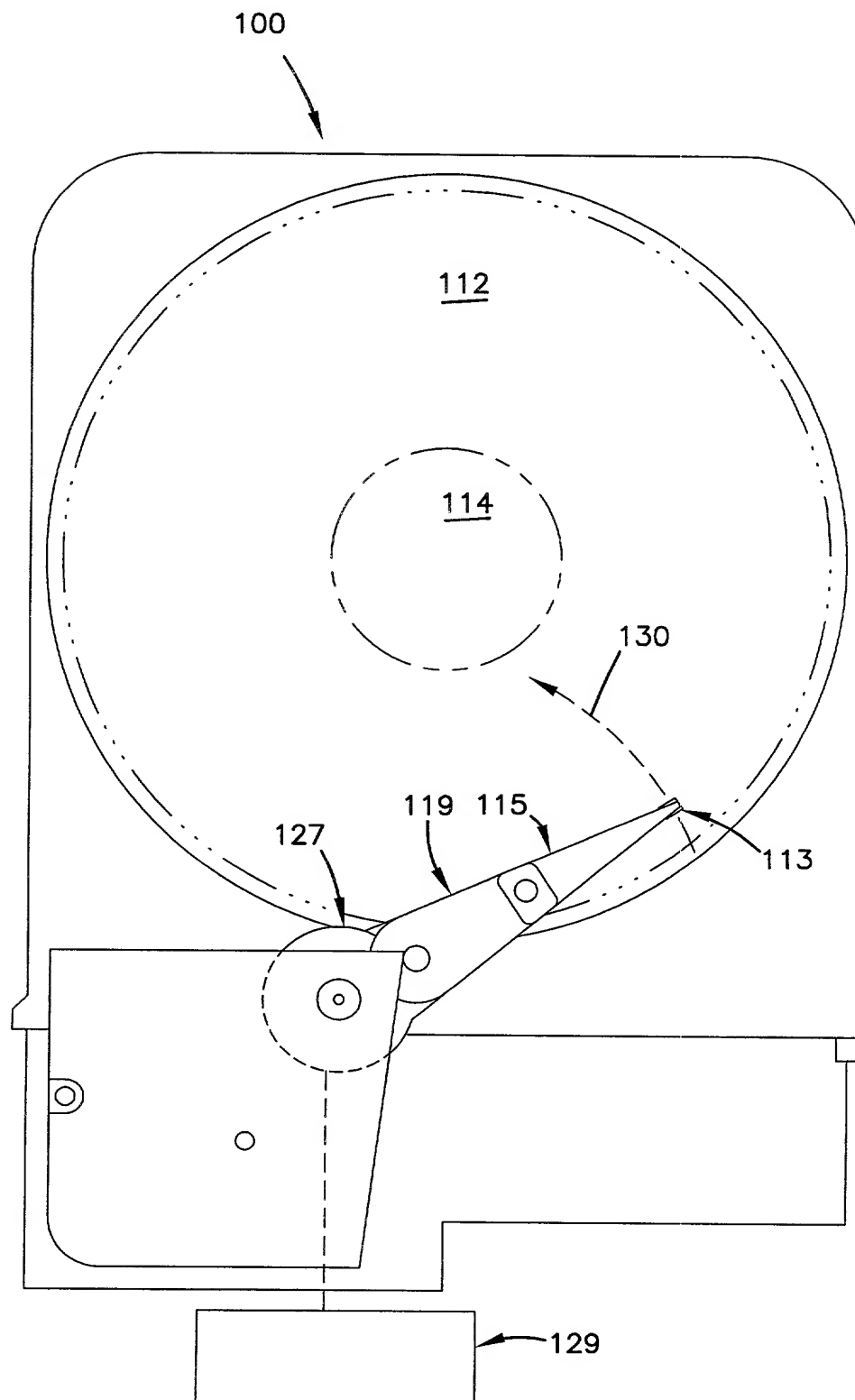


FIG. 1



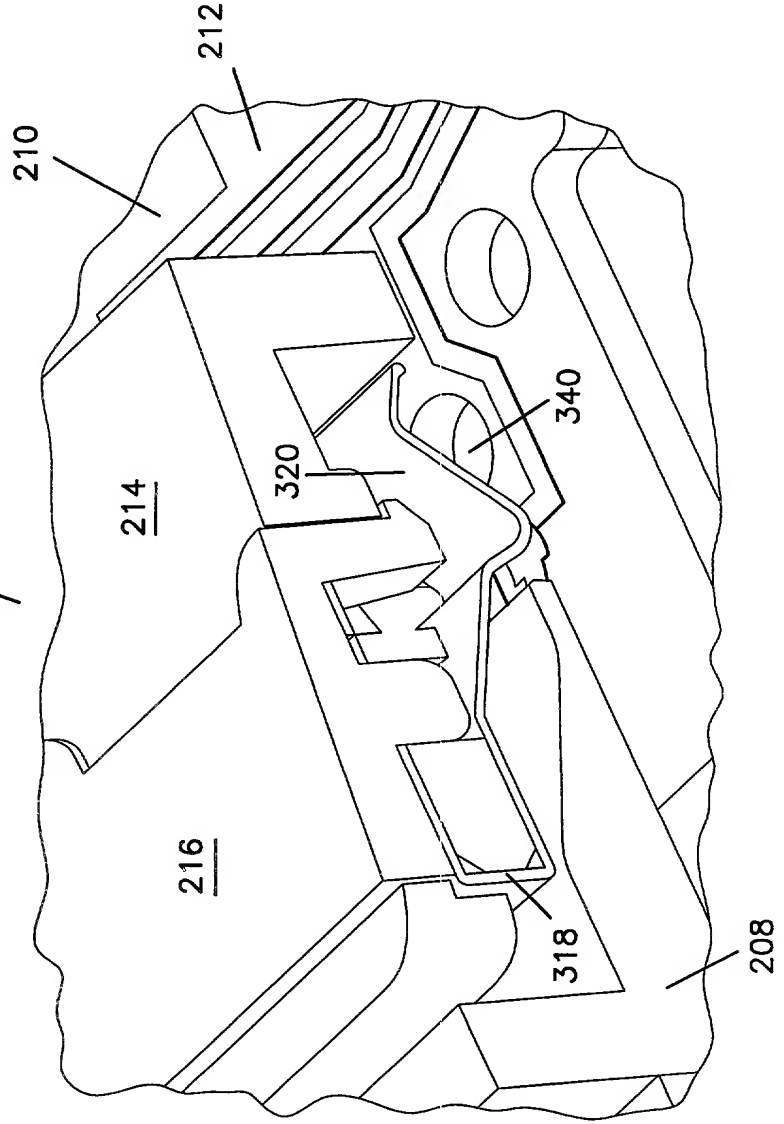
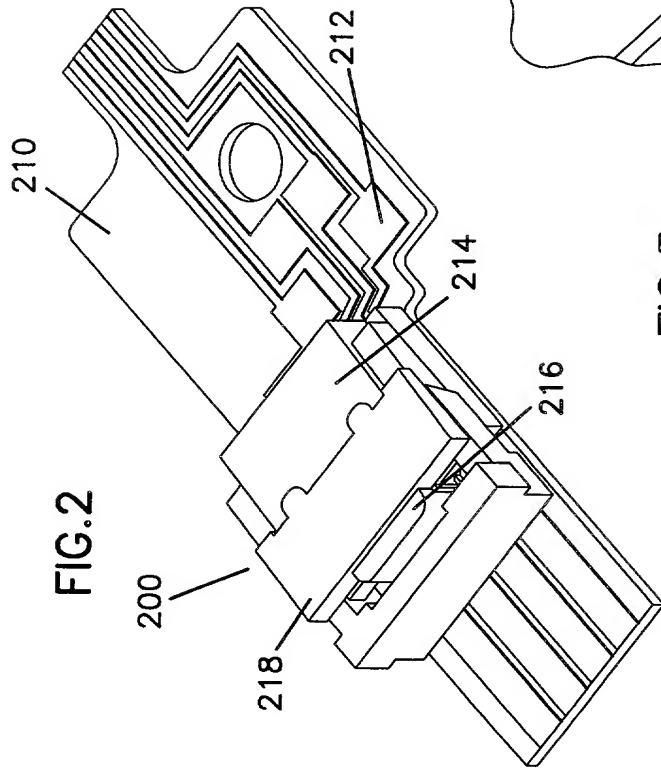


FIG. 4

FIG. 4 is a perspective view of a device 200. The device 200 includes a first substrate 210 and a second substrate 212. A conductive layer 208 is disposed on the first substrate 210. A conductive layer 214 is disposed on the second substrate 212. A conductive layer 318 is disposed on the first substrate 210. A conductive layer 320 is disposed on the second substrate 212. A conductive layer 340 is disposed on the first substrate 210. A conductive layer 340 is disposed on the second substrate 212.

A cross-sectional view of a device assembly. A base plate 200 is shown with a sloped surface 208. A component 216 is mounted on the base. A rectangular component 318 is positioned within a housing. A curved component 320 is shown in a channel, with a wavy line 520 indicating a specific feature or interface. A vertical component 540 is attached to the bottom of the assembly.

FIG. 6

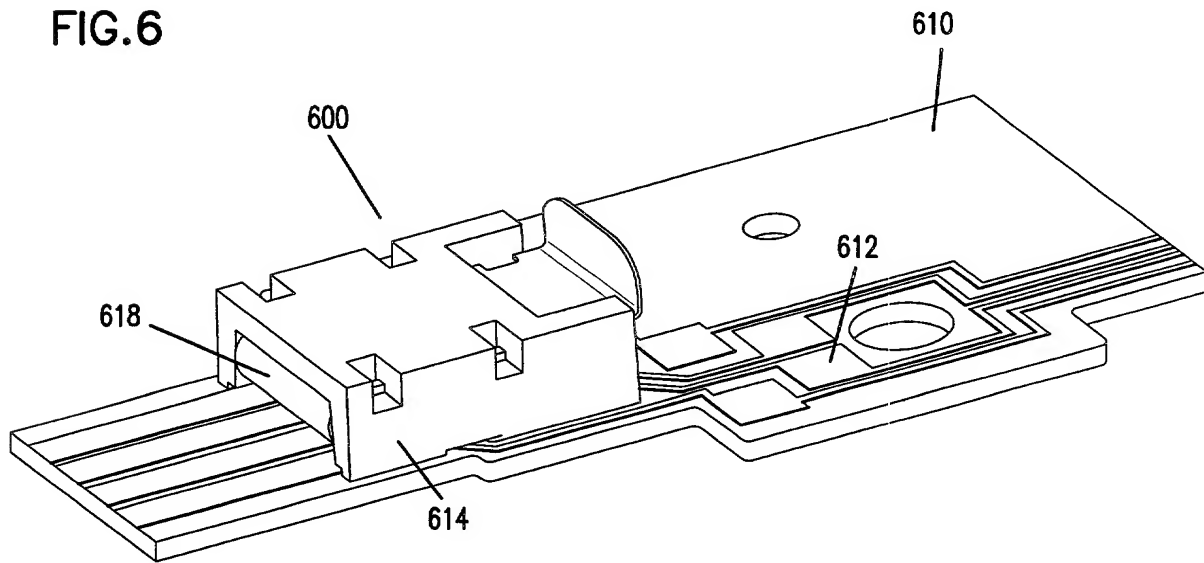
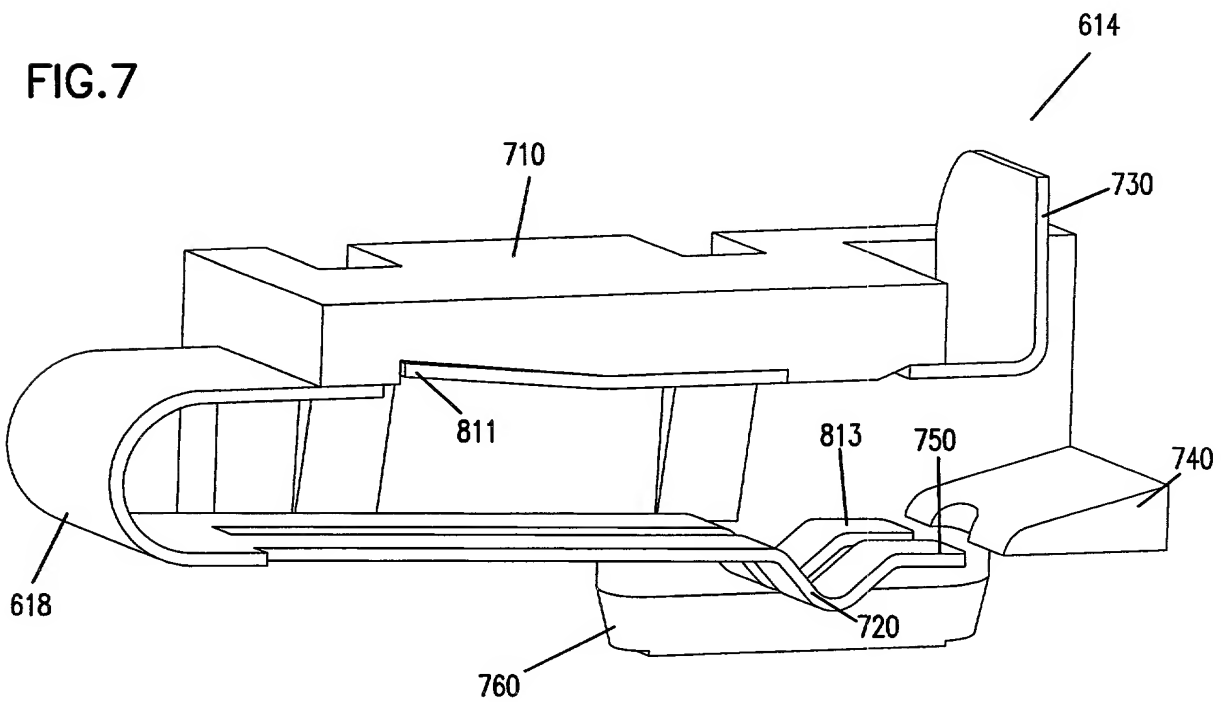


FIG. 7



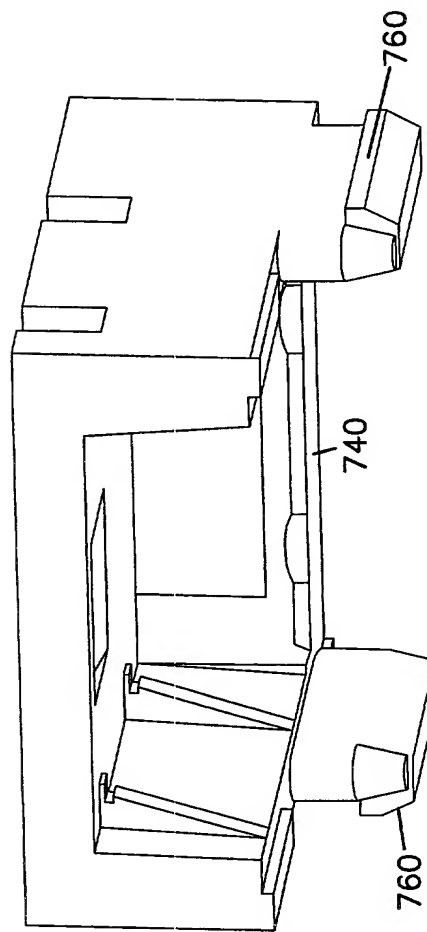
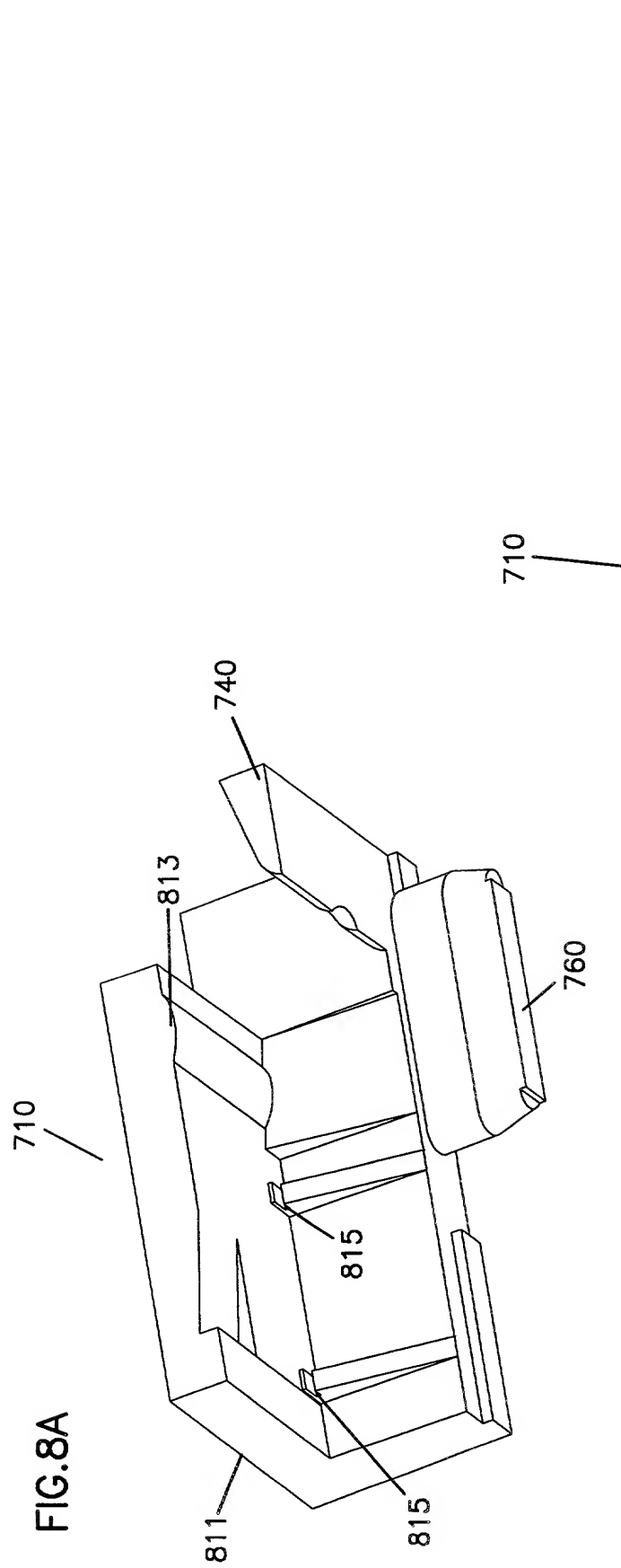


FIG.9

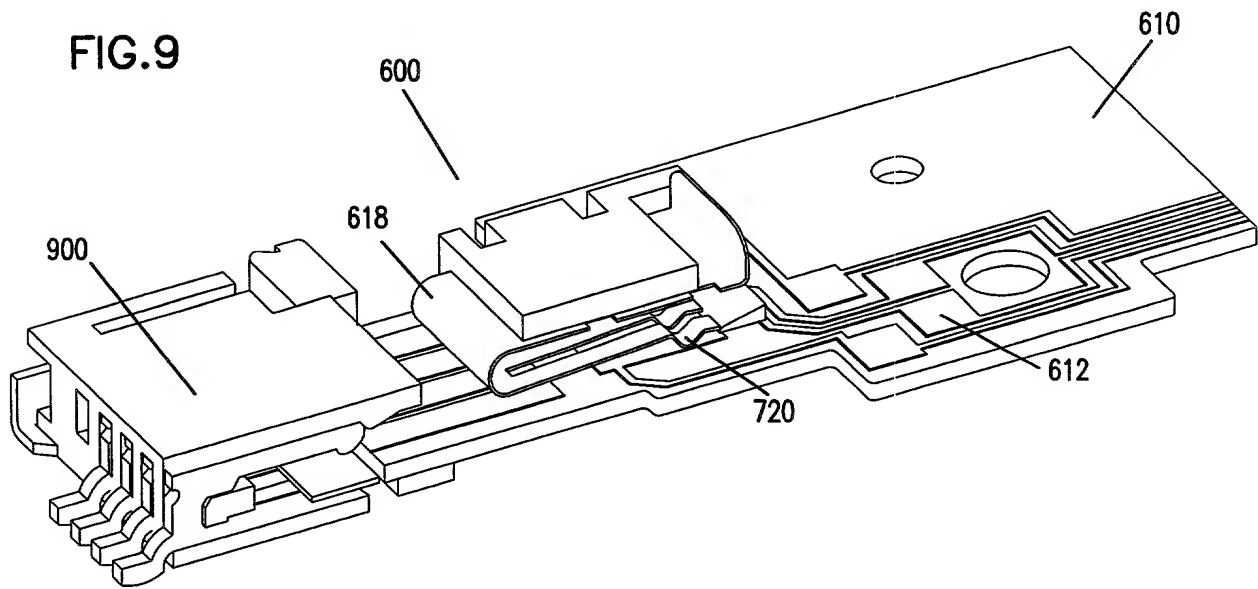


FIG.10

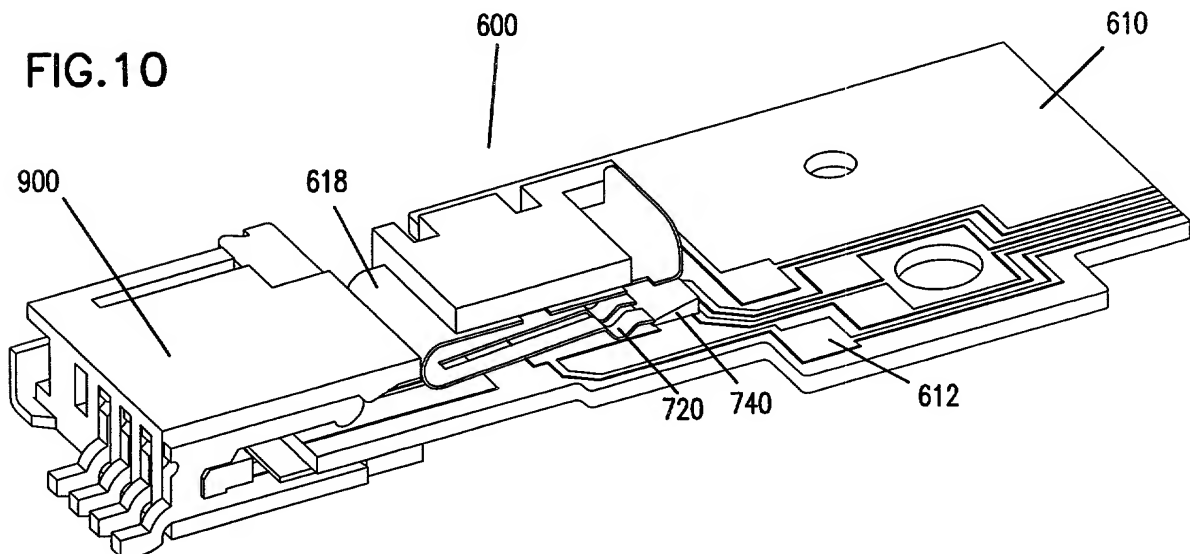
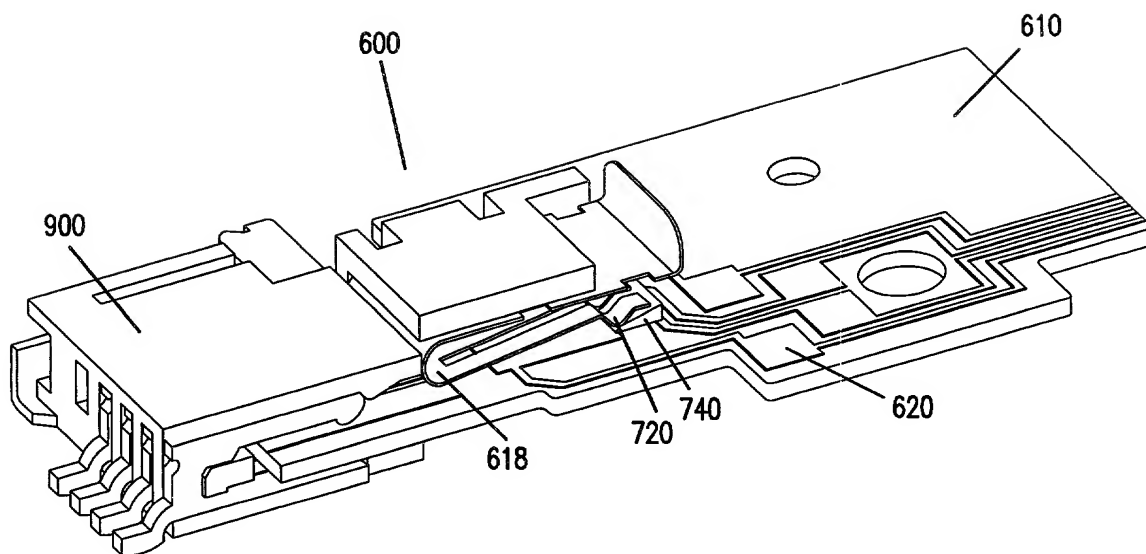


FIG. 11A



600

